

MJD112 (NPN) MJD117 (PNP)

Preferred Device

Complementary Darlington Power Transistors

DPAK For Surface Mount Applications

Designed for general purpose power and switching such as output or driver stages in applications such as switching regulators, converters, and power amplifiers.

Features

- Lead Formed for Surface Mount Applications in Plastic Sleeves (No Suffix)
- Straight Lead Version in Plastic Sleeves (“-1” Suffix)
- Electrically Similar to Popular TIP31 and TIP32 Series
- Pb-Free Packages are Available

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	100	Vdc
Collector-Base Voltage	V_{CB}	100	Vdc
Emitter-Base Voltage	V_{EB}	5	Vdc
Collector Current – Continuous – Peak	I_C	2 4	Adc
Base Current	I_B	50	mAdc
Total Power Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	20 0.16	W W/ $^\circ\text{C}$
Total Power Dissipation (Note1) @ $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	1.75 0.014	W W/ $^\circ\text{C}$
Operating and Storage Junction Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	6.25	$^\circ\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	71.4	$^\circ\text{C}/\text{W}$

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

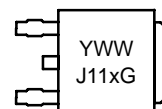
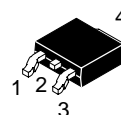
1. These ratings are applicable when surface mounted on the minimum pad sizes recommended.



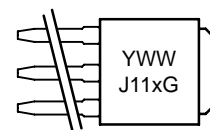
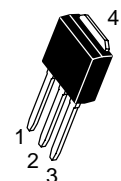
ON Semiconductor®

SILICON POWER TRANSISTORS 2 AMPERES 100 VOLTS, 20 WATTS

MARKING DIAGRAMS



DPAK
CASE 369C



DPAK-3
CASE 369D

Y = Year
WW = Work Week
x = 2 or 7
G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

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ELECTRICAL CHARACTERISTICS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector-Emitter Sustaining Voltage (Note 2) ($I_C = 30\text{ mA}$, $I_B = 0$)	$V_{CE(sus)}$	100	-	Vdc
Collector Cutoff Current ($V_{CE} = 50\text{ Vdc}$, $I_B = 0$)	I_{CEO}	-	20	μAdc
Collector Cutoff Current ($V_{CB} = 100\text{ Vdc}$, $I_E = 0$)	I_{CBO}	-	20	μAdc
Emitter Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	-	2	mAdc
Collector-Cutoff Current ($V_{CB} = 80\text{ Vdc}$, $I_E = 0$)	I_{CBO}	-	10	μAdc
Emitter-Cutoff Current ($V_{BE} = 5\text{ Vdc}$, $I_C = 0$)	I_{EBO}	-	2	mAdc

ON CHARACTERISTICS

DC Current Gain ($I_C = 0.5\text{ Adc}$, $V_{CE} = 3\text{ Vdc}$) ($I_C = 2\text{ Adc}$, $V_{CE} = 3\text{ Vdc}$) ($I_C = 4\text{ Adc}$, $V_{CE} = 3\text{ Vdc}$)	h_{FE}	500 1000 200	- 12,000 -	-
Collector-Emitter Saturation Voltage ($I_C = 2\text{ Adc}$, $I_B = 8\text{ mA}$) ($I_C = 4\text{ Adc}$, $I_B = 40\text{ mA}$)	$V_{CE(sat)}$	- -	2 3	Vdc
Base-Emitter Saturation Voltage ($I_C = 4\text{ Adc}$, $I_B = 40\text{ mA}$)	$V_{BE(sat)}$	-	4	Vdc
Base-Emitter On Voltage ($I_C = 2\text{ Adc}$, $V_{CE} = 3\text{ Vdc}$)	$V_{BE(on)}$	-	2.8	Vdc

DYNAMIC CHARACTERISTICS

Current-Gain - Bandwidth Product ($I_C = 0.75\text{ Adc}$, $V_{CE} = 10\text{ Vdc}$, $f = 1\text{ MHz}$)	f_T	25	-	MHz
Output Capacitance ($V_{CB} = 10\text{ Vdc}$, $I_E = 0$, $f = 0.1\text{ MHz}$)	C_{ob}	- -	200 100	pF
	MJD117 MJD112			

2. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.

*These ratings are applicable when surface mounted on the minimum pad sizes recommended.

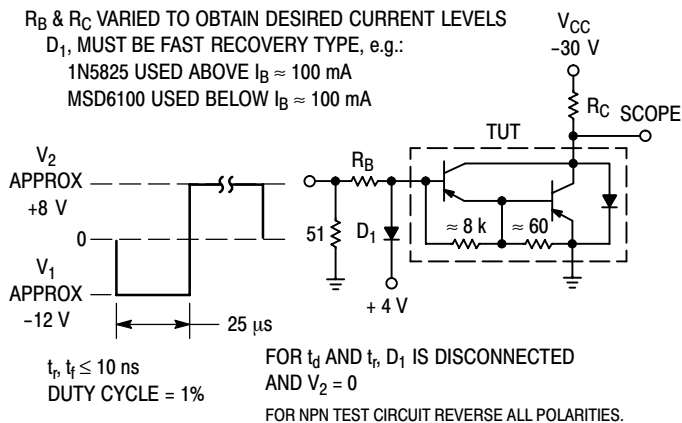


Figure 1. Switching Times Test Circuit

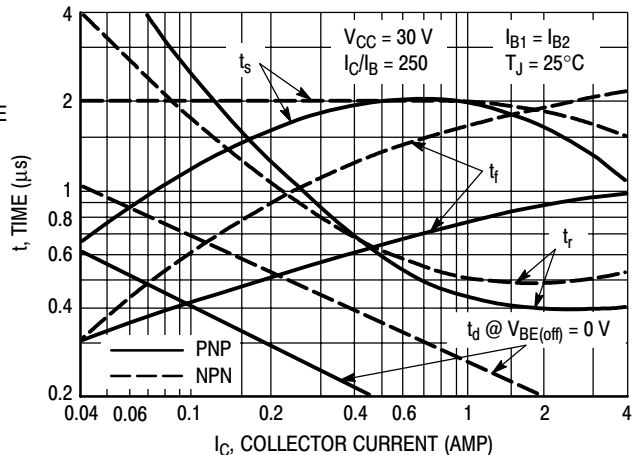


Figure 2. Switching Times

MJD112 (NPN) MJD117 (PNP)

ORDERING INFORMATION

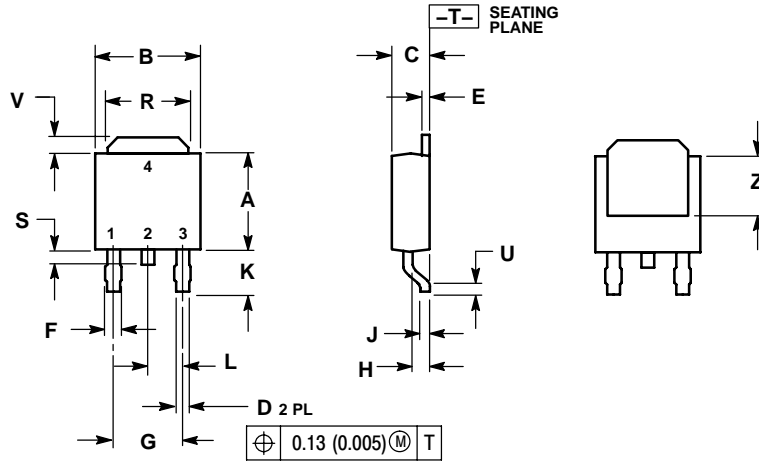
Device	Package Type	Package	Shipping†
MJD112	DPAK	369C	75 Units / Rail
MJD112G	DPAK (Pb-Free)		
MJD112-001	DPAK-3	369D	
MJD112-1G	DPAK-3 (Pb-Free)		
MJD112RL	DPAK	369C	1800 Tape & Reel
MJD112RLG	DPAK (Pb-Free)		2500 Tape & Reel
MJD112T4	DPAK		75 Units / Rail
MJD112T4G	DPAK (Pb-Free)		
MJD117	DPAK		369D
MJD117G	DPAK (Pb-Free)		
MJD117-001	DPAK-3	369C	2500 Tape & Reel
MJD117-1G	DPAK-3 (Pb-Free)		
MJD117T4	DPAK	369C	2500 Tape & Reel
MJD117T4G	DPAK (Pb-Free)		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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PACKAGE DIMENSIONS

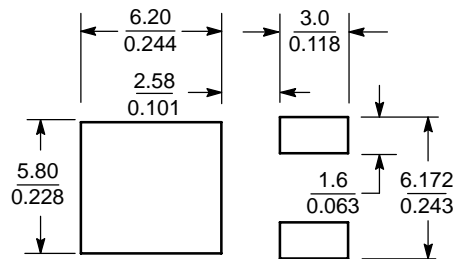
DPAK
CASE 369C
ISSUE O



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.235	0.245	5.97	6.22
B	0.250	0.265	6.35	6.73
C	0.086	0.094	2.19	2.38
D	0.027	0.035	0.69	0.88
E	0.018	0.023	0.46	0.58
F	0.037	0.045	0.94	1.14
G	0.180 BSC		4.58 BSC	
H	0.034	0.040	0.87	1.01
J	0.018	0.023	0.46	0.58
K	0.102	0.114	2.60	2.89
L	0.090 BSC		2.29 BSC	
R	0.180	0.215	4.57	5.45
S	0.025	0.040	0.63	1.01
U	0.020	---	0.51	---
V	0.035	0.050	0.89	1.27
Z	0.155	---	3.93	---

SOLDERING FOOTPRINT*



SCALE 3:1 $\left(\frac{\text{mm}}{\text{inches}}\right)$

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.